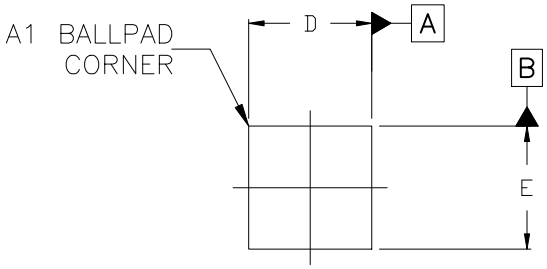
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

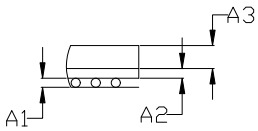
ON Semiconductor®

FCBGA121 8x8x1.35
CASE 489BR
ISSUE O

DATE 24 JUL 2019



TOP VIEW

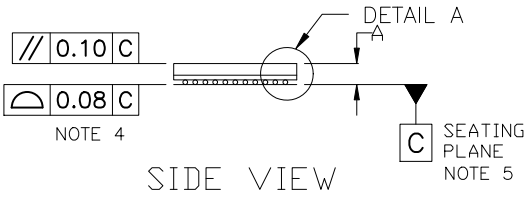


DETAIL A

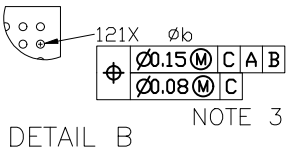
NOTES:

1. DIMENSIONING AND TOLERANCING PER. ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

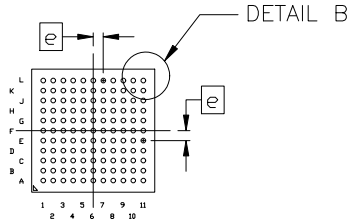
	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
A	1.15	1.25	1.35
A1	0.19	0.24	0.29
A2	0.31 REF		
A3	0.65	0.70	0.75
b	0.25	0.30	0.35
D	7.90	8.00	8.10
E	7.90	8.00	8.10
e	0.65 BSC		



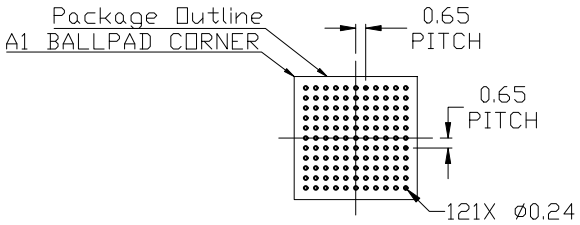
SIDE VIEW



DETAIL B



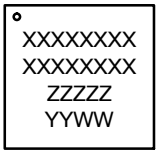
BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
ZZZZ = Assembly Lot Code
YY = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	**98AON09030H**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.	
DESCRIPTION:	**FCBGA121 8x8x1.35**		**PAGE 1 OF 1**